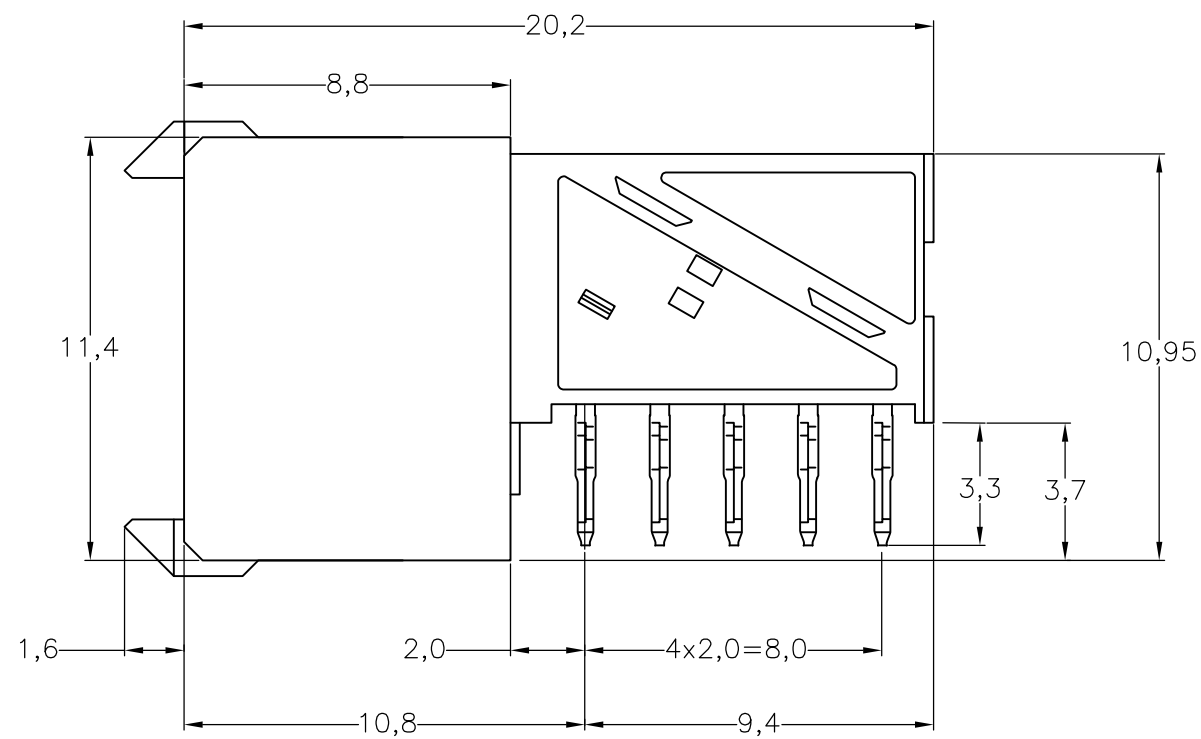
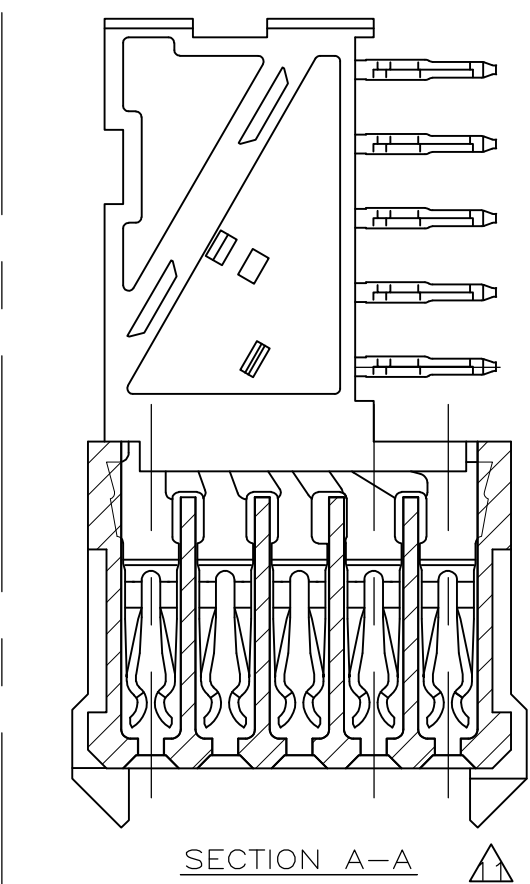
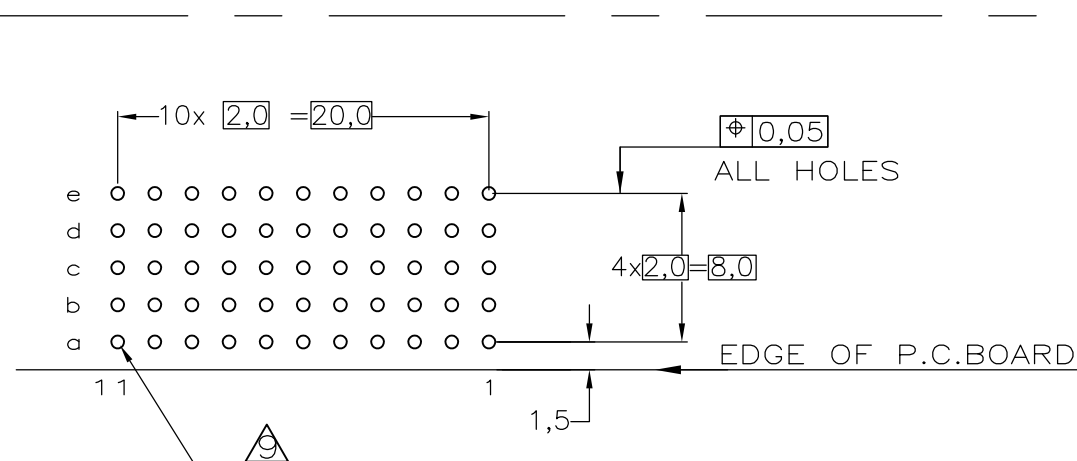




- △ MATERIAL CONTACT; PHOSPHORBRONZE MATERIAL HOUSING; GLASSFILLED POLYESTER (GRAY) UL—RATING 94VO.
- △ GENERAL PLATING SPECIFICATION: UNDERPLATING (ENTIRE CONTACT): 1,27μm NICKEL MIN. AND ACTION PIN: 0,5μm TIN—LEAD MIN. FOR PLATING OF MATING SURFACES SEE APPLICABLE SPECIFICATION REFERENCE FOR EACH DASH NUMBER.
- △ CONFORMS TO ALL TESTING ACCORDING IEC 61076—4—101 PERFORMANCE LEVEL 2.
- △ CONFORMS TO ALL TESTING ACCORDING IEC 61076—4—101 PERFORMANCE LEVEL 1.
- △ CONNECTOR TESTED AND QUALIFIED AGAINST TELCORDIA GR—1217—CORE QUALITY LEVEL III, CENTRAL OFFICE APPLICATIONS.
- △ CONNECTOR TESTED AND QUALIFIED AGAINST TELCORDIA GR—1217—CORE QUALITY LEVEL III, UNCONTROLLED ENVIRONMENT APPLICATIONS.
- △ CONNECTOR LUBRICATED WITH TELCORDIA GR—1217—CORE APPROVED LUBRICANT.
- △ CONNECTOR PRINTED WITH PARTNUMBER AND DATECODE THE MARKING CAN APPEAR ON THE FRONT SIDE OR ON THE BACK SIDE.
- △ PLATED—THROUGH HOLES AT 2x2mm SQUARE GRID. 55 HOLES
- 10 FITS WITH INTEGRATED GROUND RETURN UPPERSHIELD, BASIC P.N. 352111 AND INTEGRATED GROUND RETURN LOWERSHIELD, BASIC P.N. 352112
- △ CONNECTOR ASSEMBLED WITH REDESIGNED CONTACTS. CONTACTS HAVE A CORING—OUT IN THE PLASTIC.
- △ 0.76umMIN GOLD PLATING AT MATING SURFACES.



SCALE 2,5:1
COMPONENT SIDE AS SHOWN
RECOMMENDED PCB-HOLE LAY-OUT

P.C.B. HOLE DIM. ACTION PIN
FOR DETAILS SEE
APPLICATION SPECIFICATION

[illegible]